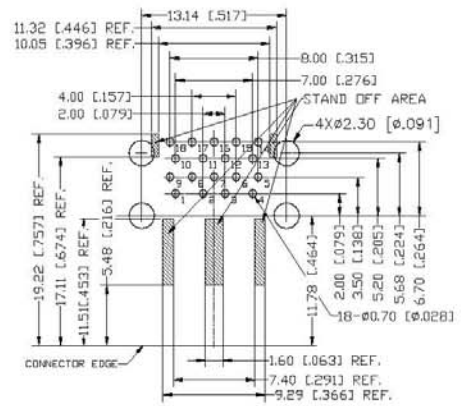
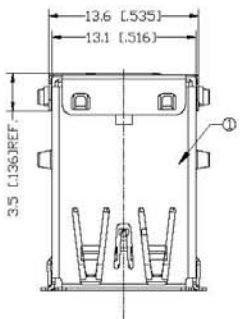
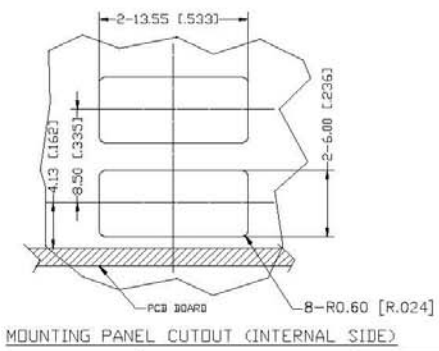
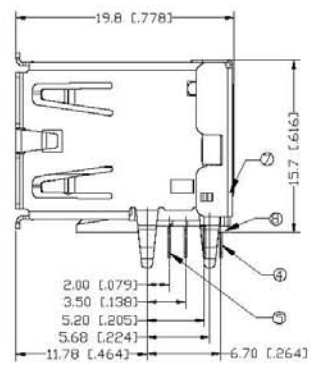
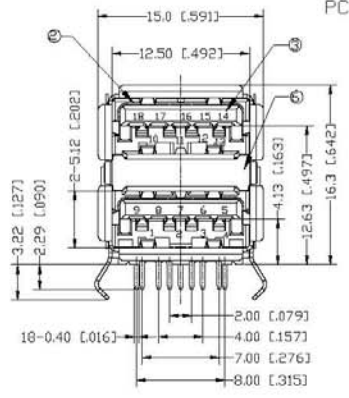


RoHS

A  
B  
C  
D  
E  
F  
G  
H



RECOMMENDED P.C.B LAYOUT (TOP VIEW)  
PCB THICKNESS: 1.60 [L063], TOLERANCE: ±0.05[L002]



REV.	ECN. NO.	NAME	DATE
1	TER11-00134	JACKY	07/04/11"
2	TER13-00010	JUNELY	01/30/13'
3	TER14-00048	JUNELY	09/11/14'

- NOTES:
- THE PRODUCT NUMBERS ARE ASSIGNED AS FOLLOW.  
5406-X 01-02 1-XX  
    - 02- RoHS(NY66)
    - H1- HALOGEN FREE(NY66)
    - PACKAGING TYPE  
1- TRAY
    - CONTACT PLATING  
0- Gold Flash/Tin
    - 3- 30u" Gold Plated/Tin
    - 6- 16u" Pd/Ni + Gold Flash/Tin
    - Q- 30u" Pd/Ni + Gold Flash/Tin
  - ELECTRICAL  
    - CONTACT RESISTANCE: VBUS & GND CONTACTS: 30 MILLIOHMS MAX; THE OTHER CONTACTS: 50 MILLIOHMS MAX.
    - INSULATION RESISTANCE: 100 MEGAOHMS MIN.
  - MECHANICAL  
    - INSERTION FORCE: 35 N MAX.
    - WITHDRAWAL FORCE: 10 N MIN.
  - ENVIRONMENTAL  
    - TEMPERATURE RANGE: -20°C TO +85°C

Pin No.	10	11	12	13	14	15	16	17	18
	1	2	3	4	5	6	7	8	9
Signal Name	VBUS	D-	D+	GND	StdA_SSRX-	StdA_SSRX+	GND_DRAIN	StdA_SSTX-	StdA_SSTX+
Remark	USB2 CONTACT PIN				USB3 CONTACT PIN				

⑧	ORGANIZER	1	NY66	Molded Color: Black, UL 94V-0
⑦	REAR SHELL	1	STAINLESS STEEL	NONE
⑥	GROUND FINGER	1	STAINLESS STEEL	NONE
⑤	USB2 CONTACT	8	COPPER ALLOY	Ni Underplating; Tin Plating at Tin Plating at Solder Area. Pd/Ni + Gold Flash Plated at Contact Area
④	USB3 CONTACT	10	COPPER ALLOY	
③	INNER INSULATOR	2	NY66	Molded Color: Blue, UL 94V-0
②	FRAME	1	NY66	Molded Color: Black, UL 94V-0
①	SHELL	1	STAINLESS STEEL	Ni Plating
ITEM	DESCRIPTION	QTY	MATERIAL	TREATMENT

		TITLE	USB 3.0 DOUBLE PORT A R/A DIP TYPE GROUND W/O SPRING CONNECTOR	
(A4)		DWG.NO.	5406-X01-021-XX(02,H1)	
APP.		TOLERANCE UNLESS OTHERWISE SPECIFIED	LINEAR	0.0 ±0.38 [0.0 ±0.15]
CHK.			UNIT:	0.00±0.25 [0.00±0.10]
DR.		mm [inch]	ANGLES	± 3'
DWG.PATH: RD\67\5406X01021XX(02,H1)-3		SCALE	1.67:1	SHEET 1 OF 1 REV: 3

A  
B  
C  
D  
E  
F  
G  
H